

Special Issue

Selected Papers from the 2016 International Conference on Advanced Manufacturing (ICAM 2016)

Message from the Guest Editor

The 2016 International Conference on Advanced Manufacturing (ICAM 2016) will be held in Sun Moon Lake, Nantou, Taiwan, 16–19 December 2016. This conference is a platform for researchers from academia, research institutes and industry to present and discuss the new developments and emerging technologies in advanced manufacturing. This Special Issue will collect selected papers submitted to the ICAM 2016. The papers will be again refereed, following the usual refereeing process in force at *Applied Sciences*. For the participants, it is an exciting opportunity to promote their research and professional work.

Guest Editor

Prof. Dr. Gou-Jen Wang

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Deadline for manuscript submissions

closed (31 January 2017)



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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